

Material Declaration Report



Package Type:	MSOP8
Pericom Package Code:	U08 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	25.355
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	Mar.05.2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	9.725	J	Silica Fused	60676-86-0	88.20	8.57745
			Epoxy resin	Secret	5.00	0.48625
			Epoxy,Cresol Novolac	29690-82-2	1.50	0.14588
			Phenol resin	Secret	5.00	0.48625
			Carbon Black	1333-86-4	0.30	0.02918
LEAD FRAME	14.412		Cu	7440-50-8	90.54	13.04862
			Fe	7439-89-6	2.35	0.33868
			P	7723-14-0	0.0825	0.01189
			Zn	7440-66-6	0.1225	0.01765
			Pb	7439-92-1	0.030	0.00432
			Silver	7440-22-4	6.87	0.99010
TERMINATION PLATING	0.6200		Tin	7440-31-5	99.90	0.61938
			Impurity	Secret	0.10	0.00062
SILICON DIE	0.350		Silicon	7440-21-3	96.100	0.33635
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.100	0.00035
			Titanium(Ti)	7440-32-6	2.800	0.00980
			Phosphorus(P)	7664-38-2	0.300	0.00105
			Boron(B)	7440-42-8	0.500	0.00175
DIE ATTACH EPOXY	0.129		Silver	7440-22-4	69.50	0.08966
			Epoxy resin	Secret	20.00	0.02580
			-Butyrolctone	96-48-0	7.50	0.00968
			Phenolic Resin	Secret	3.00	0.00387
GOLD WIRE	0.119		Au	7440-57-5	99.99	0.11899
			Other materials	Secret	0.01	0.00001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
		<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE														
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			